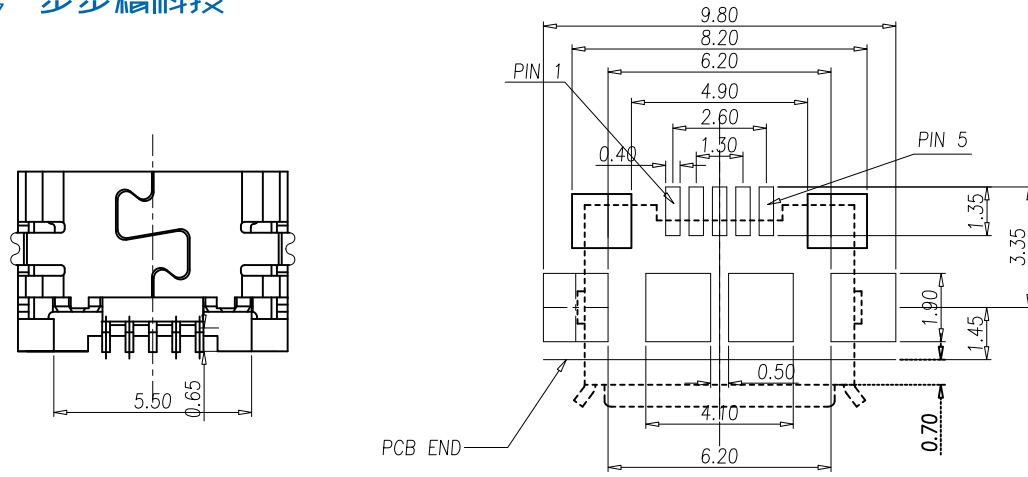
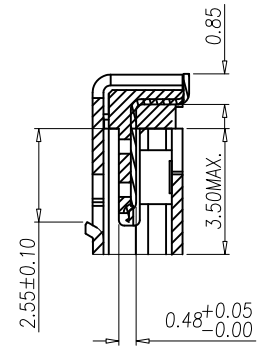
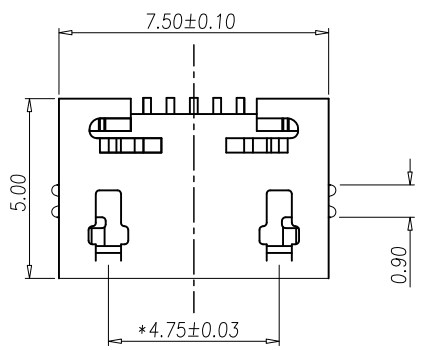
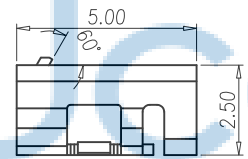
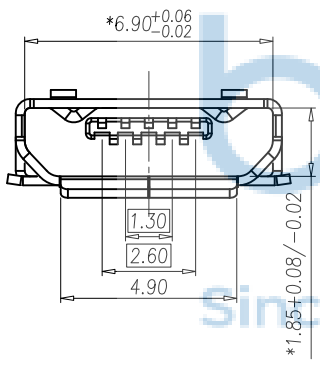


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|------|---------|---------|---------------|----------|
| REV. | ECN NO. | CONTENT | DATE | ENGINEER |
| AO | | | 2023 20/04 | |



RECOMMEND P.C.B.LAYOUT



NOTES:

MATERIALS

- HOUSING:
HI-TEMP. PLASTIC UL 94V-0 BLACK
- CONTACT
COPPER ALLOY, T=0.15mm
GOLD PLATED ON CONTACT AREA
GOLD FLASH PLATED ON SOLDER TAILS UNDER NICKEL PLATED
- SHELL:
STAINLESS STEEL OR COPPER ALLOY T=0.3mm
MATTE TIN PLATING OVERALL UNDER NICKEL PLATED

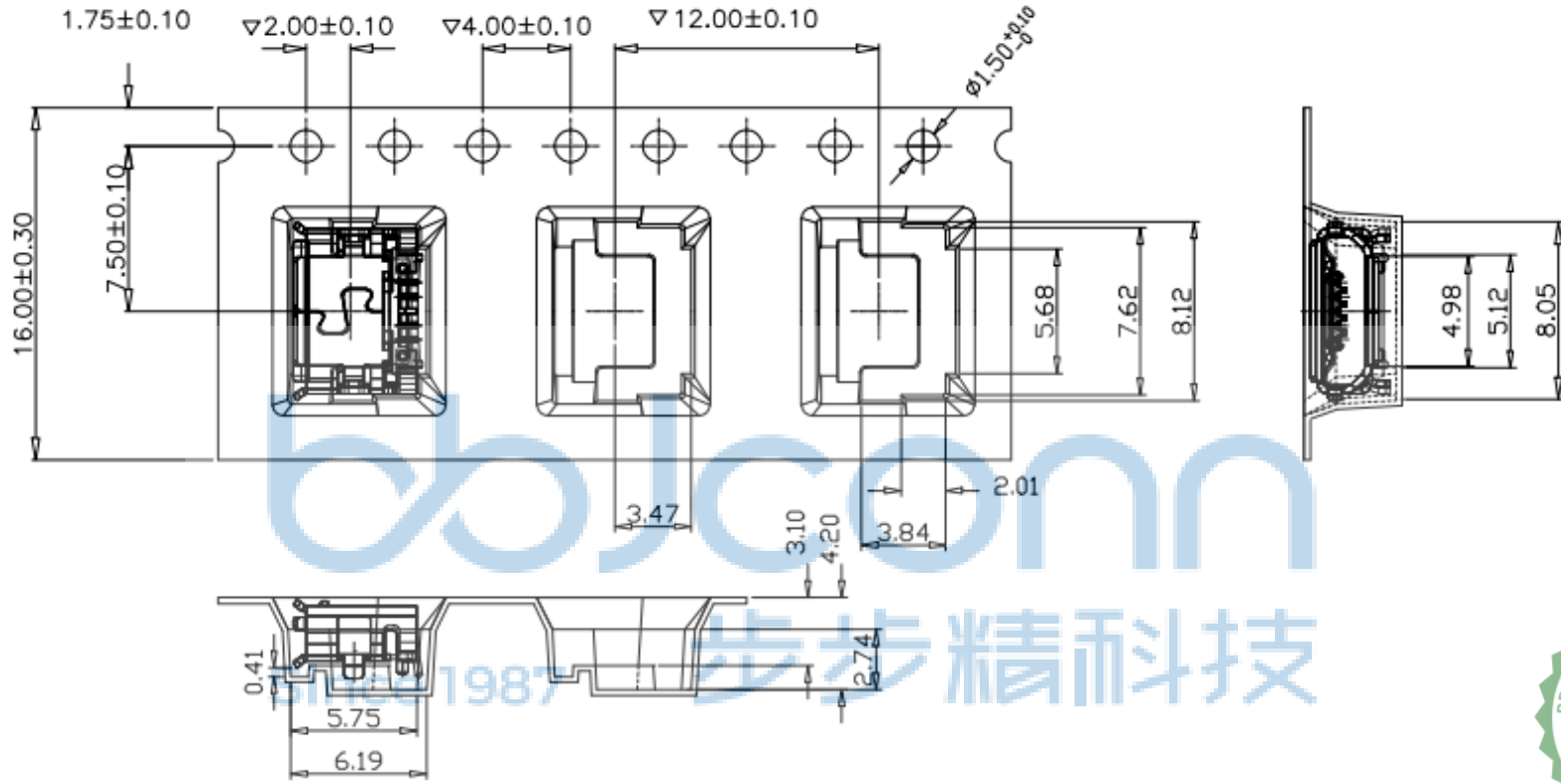
SPECIFICATIONS

- VOLTAGE RATING:30V AC
- CURRENT RATING:WHEN APPLYING CURRENT ONLY TO SIGNAL TERMINALS:
1.0A(FOR TERMINAL NO. 2,3 AND 4)
WHEN APPLYING CURRENT ONLY TO POWER TERMINALS:
1.8A(FOR TERMINAL NO. 1 AND 5)
0.5A(FOR TERMINAL NO. 2,3 AND 4)
- INSULATION RESISTANCE:100M MINIAT 100V DC
- DIELECTRIC WITHSTANDING VOLTAGE:100V(r. m. s)AC FOR 1 MINUTE
- CONTACT RESISTANCE:30m MAX.
- OPERATING TEMPERATURE:-30 TO +80°C



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|--|--|---------------------------------------|--|---|----------|
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| | APPD. JM_Zheng 23/05'02 | PJ. NO.: MC.01.42-11-J001 | | SIZE: A4 DRW NO.: | |
| PDWG.NO: 0526-1 | DR. SGF 23/05'02 | FINISH: SEE NOTES MAT'L.: SEE NOTES | | SCALE: N/A | REV.: A3 |
| | | UNIT: mm | | PAGE: 1/1 | |

| | | | | |
|------|--------|---------|---------------|----------|
| REV. | ECN NO | CONTENT | DATE | ENGINEER |
| A0 | | | 2023 20/04 | |



NOTE:

- 10 sprocket hole pitch cumulative tolerance ± 0.20 .
- Carrier camber is within 1mm Max. in 250mm.
- All dimensions meet EIA-481-D requirements.
- Material: Polystyrene
- Thickness: $0.3t$
- Recommend hub diameter: _____ mm.
- Packing length per 22" reel: _____ Meters; per 13" reel: 12.5 Meters.
- Component load per 13" reel: 1500 pcs.

| | |
|------|-----------------------|
| 封箱方式 | 顶部、底部“一”字封箱法 |
| 标签 | 贴外箱标签, 并在外箱标签上编序号 |
| 圆盘 | 13"16宽普通, 横着放 |
| 纸箱 | 345*345*355 纸箱; 16R/箱 |
| 项目 | 要求 |

| | | | | | |
|---|-------------------|--|--|--|--|
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| APPD. | JM_Zheng 23/05'02 | | | | |
| CHKD. | LYX 23/05'02 | | | | |
| DR. | SGF 23/05'02 | | | | |
| PDWG.NO: | 0526-1 | | | | |